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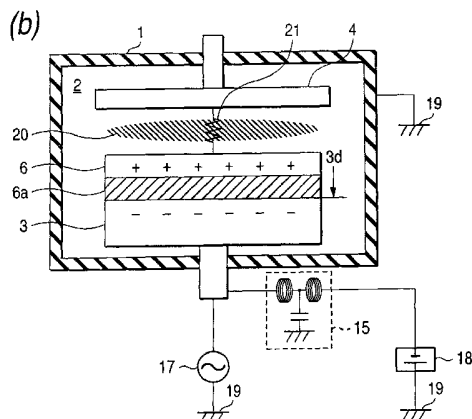
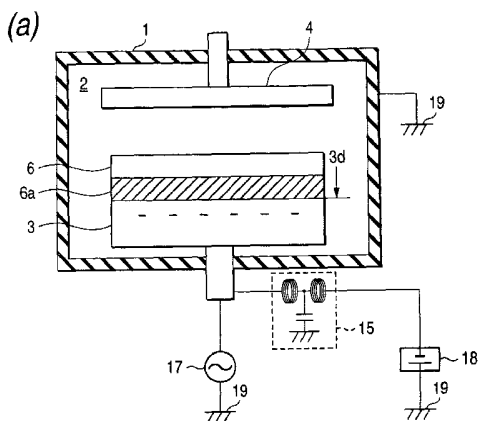
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(54) Title: PLASMA TREATING APPARATUS AND PLASMA TREATING METHOD



(57) Abstract: In a plasma treating apparatus for carrying out a plasma treatment over a silicon wafer (6) having a protective tape (6a) stuck to a circuit formation face, the silicon wafer (6) is mounted on a mounting surface (3d) which is provided on an upper surface of a lower electrode (3) formed of a conductive metal with the protective tape (6a) turned toward the mounting surface (3d). When a DC voltage is to be applied to the lower electrode (3) by a DC power portion (18) for electrostatic adsorption to adsorb and hold the silicon wafer (6) onto the lower electrode (3) in the plasma treatment, the protective tape (6a) is utilized as a dielectric for the electrostatic adsorption. Consequently, the dielectric can be thinned as much as possible and the silicon wafer (6) can be held by a sufficient electrostatic holding force.



European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

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INTERNATIONAL SEARCH REPORT

International Application No

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A. CLASSIFICATION OF SUBJECT MATTER
 IPC 7 H01L21/00 H01L21/68

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
 IPC 7 H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

WPI Data, PAJ, EPO-Internal

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
A	US 5 851 641 A (MATSUSHITA TAKAYA ET AL) 22 December 1998 (1998-12-22) figure 1 column 6, line 54 -column 7, line 28 ---	1, 12
A	PATENT ABSTRACTS OF JAPAN vol. 017, no. 672 (E-1474), 10 December 1993 (1993-12-10) & JP 05 226468 A (MITSUBISHI ELECTRIC CORP), 3 September 1993 (1993-09-03) abstract ---	1, 12
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☐ Further documents are listed in the continuation of box C.

☒ Patent family members are listed in annex.

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Date of the actual completion of the international search

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INTERNATIONAL SEARCH REPORT

Information on patent family members

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